# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

### Marketing Name / Model
[List multiple models if applicable.]

| HP ENVY 15 Laptop PC / Kerbal / G3F |

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP’s Sustainability Contact.

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>1</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</td>
<td>Battery(ies) are attached to the product by (check all that apply with an “x” inside the “[ ]”): [x] screws [ ] snaps [ ] adhesive [ ] other. Explain ______</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps 15.6”</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>DC Cable for External Power Supply</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

HPI instructions for this template are available at [EL-MF877-01](#).
## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>screw driver</td>
<td>#1</td>
</tr>
</tbody>
</table>

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Remove base screws 5pcs
2. Disassemble base cover from the unit.(rear side use tear down stick)
3. Take off 6 pcs of screws which fastening battery to Top_assy. and then disassembly the Battery
4. Unfasten 7screws and disassemble thermal module
5. Untie the LVDS cable and DC-in cable, remove 6 screws on CPU fan and GPU fan, and remove it
6. Remove DDR module(s) and SSD module(s).
7. Remove KB BL FPC, KB MEM, TP FFC, Antenna cable, DB to MB FFC, speaker cable, IR sensor FFC, FPS FPC which under SSD thermal PAD
8. Remove 5 pcs of screws and disassemble MB
9. Remove 4 pcs of screws and disassemble hinge-up assy(The LCD must open to 90 degree angle for disassemble)
10. Remove 1 pcs of screws and disassemble IO DB
11. Remove pcs of screws and disassemble IR DB
12. Remove 2 pcs of screws and disassemble speaker
13. Remove 7 pcs of screws and disassemble touchpad module and touchpad bracket
14. Remove DC-in cable
15. Disassemble LCD bezel from display unit.
16. Stretch 2 tapes under LCD panel and take LCD out
17. Disassemble camera with tear down stick
18. Disassemble camera FFC and LVDS cable, antenna
19. Loose 4 pcs of screws on each side and remove hinges R from LCD cover

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
3.2.1 Total part disassembly

3.2.2 Remove base cover.

3.2.3 Remove Battery

3.2.4 Thermal module and Fan

3.2.5 MB, SSD module, DDR module
3.2.6 hinge-up

3.2.7 Speaker, touchpad module, touchpad bracket, DC-in cable, IO board, IR board

3.2.8 LCD Bezel

3.2.9 LCD cover and LCD module
3.2.10 LCD cable, Antenna cable and Camera module

3.2.11 Hinge R and L